Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	(("2002048531") or ("2002132101") or ("2002187312") or ("2002020053") or ("5910943")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2007/06/12 05:06
L2	1244	(etch\$3) near (substrate or wafer) near (expos\$3 or open\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:23
L3	1040	(etch\$3) near (substrate or wafer) near (expos\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:32
L4	1614	micromachine\$1 near device	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:14
L5	10	3 and 4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:14
L6	15	("4783821"   "5001993"   "5006749"   "5025346"   "5049775"   "5072288"   "5129262"   "5138216"   "5162691"   "5248912"   "5260596"   "5339289"   "5366587"   "5396066"   "5418771").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/06/12 05:17
L7	37	("5633552").URPN.	USPAT	OR	ON .	2007/06/12 05:30
L8	1914	microactuator	USPAT	OR	ON	2007/06/12 06:53
L9	5	3 and 8	USPAT	OR	ON	2007/06/12 06:22
L10	50820	(etch\$3) near (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:40
L11	425	8 and 10	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:33
L12	1	(etch\$3) near (substrate or wafer) near microactuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:40
L13	20	((etch\$3) near (substrate or wafer)) with microactuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:11
L14	39	((etch\$3) near (substrate or wafer)) same microactuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:49
L15	6	2 and 8	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:49

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L16	2	("5622897"   "5804083").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/06/12 05:49
L17	11	("6130689").URPN.	USPAT	OR	ON	2007/06/12 05:50
L18	385	((etch\$3) near (substrate or wafer)) with actuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:22
L19	430	((etch\$3 or cut\$4 or divid\$3) near (substrate or wafer)) with actuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:14
L20	11	((divid\$3) near (substrate or wafer)) with actuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:12
L21	80442	((etch\$3 or cut\$4 or divid\$3) near (substrate or wafer))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:15
L22	5456	((membrane\$1) near (substrate or wafer))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:15
L23	752	21 and 22	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:15
L24	2	19 and 22	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:15
L25	20	("4533082"   "4574327"   "4605167"   "4894664"   "5110712"   "5152456"   "5255016"   "5387314"   "5513431"   "5518179"   "5716533"   "5828394"   "5870123"   "5876497"   "5938117"   "6000787"   "6010461"   "6045710"   "6234608"   "6291927").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/06/12 06:16
L26	6	2 and 8	USPAT	OR	ON	2007/06/12 06:22
L27	83	2 and actuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:22
L28	2	((etch\$3) near (substrate or wafer) near (expos\$3 or open\$3)) same actuator	US-PGPUB; USPAT; EPO; JPO	OR ·	ON	2007/06/12 06:24
L29	83	((etch\$3) near (substrate or wafer) near (expos\$3 or open\$3)) and actuator	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 06:25
L30	0	29 and 29/417.ccls.	US-PGPUB; USPAT; EPO; JPO	.OR	ON	2007/06/12 06:25

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L31	. 15	("4783821"   "5001993"   "5006749"   "5025346"   "5049775"   "5072288"   "5129262"   "5138216"   "5162691"   "5248912"   "5260596"   "5339289"   "5366587"   "5396066"   "5418771").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/06/12 06:31
L32	37	("5633552").URPN.	USPAT	OR	ON	2007/06/12 06:52
L33	4633	(portion) near (substrate or wafer) near (open\$3 or expos\$3)	USPAT	OR	OŅ	2007/06/12 06:52
L34	186	33 and \$5actuator	USPAT	OR	ON	2007/06/12 06:53
L35	2	(remov\$3 or divid\$3 or separat\$3 or cut\$4 or etch\$3) near sbustrate	USPAT	OR	ON	2007/06/12 06:55
L36	63831	(remov\$3 or divid\$3 or separat\$3 or cut\$4 or etch\$3) near substrate	USPAT	OR	ON ·	2007/06/12 06:55
L37	90	34 and 36	USPAT	OR	ON	2007/06/12 06:55
S1	15	"6103399"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/10 16:04
S2	9327	29/611,592.1,840-846.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
<b>S</b> 3	3183	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/10 16:05
S4	805	361/803.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/10 16:06
S5	1268	439/65,329.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/10 16:06
S6	49	977/724.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/10 16:06
S7	8	JAGER-EDWIN.in. or KROGH-MAGNUS.in.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:43
S8	4	S7 and micromachine\$1	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:14
S9	2	(("5771902") or ("5819749")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2007/06/11 12:45
S10	5454	membrane near (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:51

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S11	111622	(etch\$3 or remov\$3 or open\$3) near (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:58
S12	1261	S10 and S11	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:47
S13	278	S10 same S11	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:47
S14	7112	membrane near expos\$3	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:47
S15	81	S13 and S14	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:47
S16	10197	29/417,611,592.1,840-846.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S17	0	S15 and S16	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S18	805	361/803.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S19	27	S18 and S16	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S20	3183	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S21	24	S20 and S16	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S22	1268	439/65,329.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S23	20	S22 and S16	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:48
S24	68	S19 or S21 or S23	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:49
S25	0	S15 and S18	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:49

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S26	1	S15 and S20	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:49
S27	0	S15 and S22	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:49
S28	27	(membrane near (substrate or wafer)) with (membrane near expos\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:56
S29	95	((first near layer) near (substrate or wafer)) with ((first near layer) near expos\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:57
S30	8	((first near layer) near (substrate or wafer)) with ((first near layer) near expos\$3 near (etch\$3 or remov\$3 or open\$3))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:57
S31	9819	(etch\$3 or remov\$3 or open\$3) near (substrate or wafer) near (expos\$3 or open\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/12 05:12
S32	165	S31 and (substrate near frame)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 12:59
S33	3	S16 and S32	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:02
S34	0	S18 and S32	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:02
S35	3	S20 and S32	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:02
S36	0	S22 and S32	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:02
S37	105	S16 and S31	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:02
S38	8	S18 and S31	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:03
S39	63	S20 and S31	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:03
S40	4	S22 and S31	US-PGPUB; USPAT; EPO; JPO	OR .	ON	2007/06/11 13:03

S41	0	S37 and S38 and S39 and S40	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:03
S42	178	S37 or S38 or S39 or S40	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:04
S43	6	S42 and micromachine\$1	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/06/11 13:04

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